

RV1S9160A

R08DS0167EJ0101

Rev.1.01

Mar 06, 2020

HIGH CMR, 15Mbps CMOS OUTPUT, LOW FORWARD-CURRENT(I_F) 3.3V/5V OPERATION,
5-PIN SOP PHOTOCOUPLER

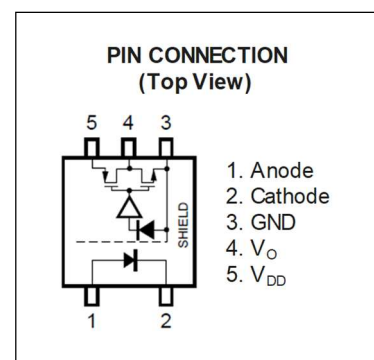
DESCRIPTION

The RV1S9160A is a photocoupler featuring high-speed switching up to 15Mbps with active low output logic which consist of an AlGaAs LED on the input side and an integrated circuit with a photodiode on the output.

This product enables to low current operation on 3.3V/5V power supply with high noise-tolerant CMR:50kV/us min. and high temperature operation up to $T_A = 125^\circ\text{C}$ in logic interface circuit.

FEATURES

- High speed communication (15 Mbps)
- High temperature operation (-40 to $+125^\circ\text{C}$)
- High common mode (dv/dt) tolerant ($CM_H, CM_L = \pm 50 \text{ kV}/\mu\text{s}$ MIN.)
- High isolation voltage ($BV = 3750 \text{ Vr.m.s.}$)
- Low input drive current ($I_{FHL} = 2.0 \text{ mA MAX.}$)
- Low voltage power supply operation ($V_{DD} = 2.7 \text{ V} \sim 5.5 \text{ V}$)
- Low pulse width distortion ($PWD = 20 \text{ ns MAX.}$)
- Ordering number of tape product :
RV1S9160ACCSP-100x#KC0 : 2500 pcs/reel
- Pb free product
- Safety standards approval
UL : UL1577, Double protection
CSA : CAN/CSA-C22.2 No.62368-1, Basic insulation
VDE : DIN EN 60747-5-5 (Option)



TRUTH TABLE

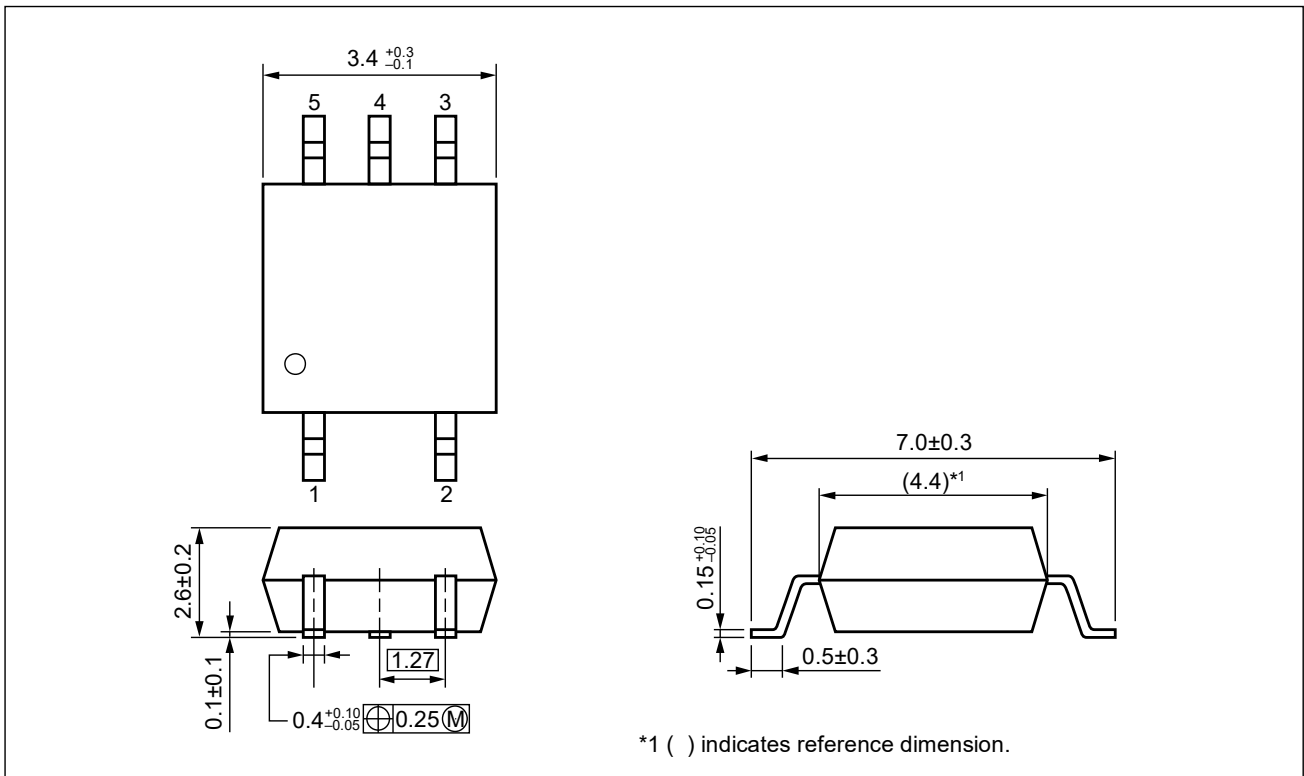
LED	OUTPUT
ON	L
OFF	H

APPLICATIONS

- Industrial inverter
- AC Servo
- FA Network
- Measurement, Control Equipment

Start of mass production
Jun.2019

PACKAGE DIMENSIONS (UNIT : mm)



Weight: 0.08g (typ.)

PHOTOCOUPLER CONSTRUCTION

Parameter	MIN.
Air Distance	4.2 mm
Creepage Distance	4.2 mm
Isolation Distance	0.2 mm

MARKING EXAMPLE

9160
N131
®

← Type Number *)
← Assembly Lot
← Bar : Pb-Free

No. 1 pin Mark
Initial of Renesas
(Engraved R)

N 1 31
Week Assembled
Year Assembled (Last 1 Digit)
Rank Code

*Applicable type numbers are listed below.

*) RV1S9160ACCSP-100x

Marking type number. "RV1S" and "ACCSP-100x" are omitted from original type number.

ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
RV1S9160ACCSP-100C	RV1S9160ACCSP-100C#SC0	Pb-Free (Ni/Pd/Au)	20 pcs (Tape 20 pcs cut)	Standard products (UL, CSA approved)	RV1S9160A
	RV1S9160ACCSP-100C#KC0		Embossed Tape 2 500 pcs/reel		
RV1S9160ACCSP-100V	RV1S9160ACCSP-100V#SC0		20 pcs (Tape 20 pcs cut)	UL, CSA, DIN EN 60747-5-5 approved	
	RV1S9160ACCSP-100V#KC0		Embossed Tape 2 500 pcs/reel		

Notes: *1. For the application of the Safety Standard, following part number should be used.

ABSOLUTELY MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current *1	I_F	20	mA
	Reverse Voltage	V_R	5	V
Detector	Supply Voltage	V_{DD}	6	V
	Output Voltage	V_O	6	V
	Output Current	I_O	10	mA
	Power Dissipation *2	P_c	200	mW
Isolation Voltage *3		BV	3 750	Vr.m.s.
Operating Ambient Temperature		T_A	-40 to +125	$^\circ\text{C}$
Storage Temperature		T_{stg}	-55 to +150	$^\circ\text{C}$

Notes: 1. Reduced to 0.93 mA/ $^\circ\text{C}$ at $T_A = 110^\circ\text{C}$ or more
 2. Reduced to 4.57 mW/ $^\circ\text{C}$ at $T_A = 90^\circ\text{C}$ or more
 3. AC Voltage for 1minute at $T_A = 25^\circ\text{C}$, RH = 60% between input and output.
 Pins 1-2 shorted together, 3-5 shorted together.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Low Level forward voltage	V_{FL}	0		0.8	V
High Level Forward Current	I_{FH}	3		6	mA
Supply Voltage	V_{DD}	2.7		5.5	V

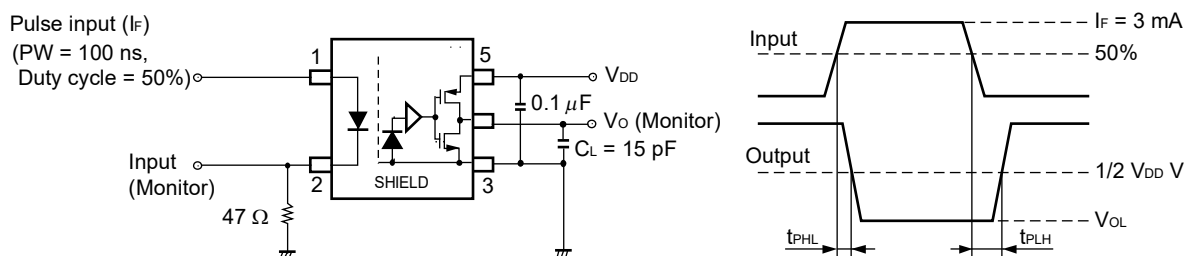
ELECTRICAL CHARACTERISTICS

(T_A = - 40 to +125°C, V_{DD} = 2.7 to 5.5 V, unless otherwise specified)

Parameter		Symbol	Conditions	MIN.	TYP.*1	MAX.	Unit
Diode	Forward Voltage	V_F	$I_F = 6 \text{ mA}$, T _A = 25°C	1.4	1.55	1.7	V
	Reverse Current	I_R	$V_R = 3 \text{ V}$, T _A = 25°C			10	μA
	Terminal Capacitance	C_t	$V_F = 0 \text{ V}$, f = 1 MHz, T _A = 25°C		30		pF
Detector	High Level Output Current	I_{DDH}	$I_F = 0 \text{ mA}$		1.1	2	mA
	Low Level Output Current	I_{DDL}	$I_F = 3 \text{ mA}$		1.0	2	
	High Level Output Voltage	V_{OH}	$I_O = -3.2 \text{ mA}$, $I_F = 0 \text{ mA}$	$V_{DD}-1.0$	V_{DD}		V
			$I_O = -20 \text{ μA}$, $I_F = 0 \text{ mA}$	$V_{DD}-0.1$	V_{DD}		
	Low Level Output Voltage	V_{OL}	$I_O = 3.2 \text{ mA}$, $I_F = 3 \text{ mA}$		0.13	0.4	
			$I_O = 20 \text{ μA}$, $I_F = 3 \text{ mA}$		0.001	0.1	
Coupled	Threshold Input Voltage (H to L)	I_{FHL}	$V_O < 0.4 \text{ V}$		1.0	2.0	mA
	Isolation Resistance	R_{I-O}	$V_{I-O} = 1 \text{ kV}_{DC}$, RH = 40 to 60%, T _A = 25°C	10 ¹¹			Ω
	Isolation Capacitance	C_{I-O}	$V = 0 \text{ V}$, f = 1 MHz, T _A = 25°C		0.5		pF
	Propagation Delay Time (H to L)*2	t_{PHL}	$I_F = 3 \text{ mA} \leftrightarrow 0 \text{ mA}$ $V_{DD} = 3.3 \text{ V}, 5 \text{ V}$ $C_L = 15 \text{ pF}$		40	60	ns
	Propagation Delay Time (L to H)*2	t_{PLH}			38	60	
	Pulse Width Distortion*2	PWD			2	20	
	Propagation Delay Skew	t_{PSK}				25	
	Rise Time	t_r			5		
	Fall Time	t_f			5		
	Common Mode Transient Immunity at High Level Output*3	$ CM_H $	$I_F = 0 \text{ mA}$, $V_O > 4 \text{ V}$ ($V_{DD} = 5 \text{ V}$), $V_O > 2.3 \text{ V}$ ($V_{DD} = 3.3 \text{ V}$), $V_{CM} = 1.5 \text{ kV}$, T _A = 25°C	50	60		kV/μs
	Common Mode Transient Immunity at Low Level Output*3	$ CM_L $	$I_F = 3 \text{ mA}$, $V_O < 0.4 \text{ V}$ ($V_{DD} = 3.3 \text{ V}, 5 \text{ V}$), $V_{CM} = 1.5 \text{ kV}$, T _A = 25°C	50	60		

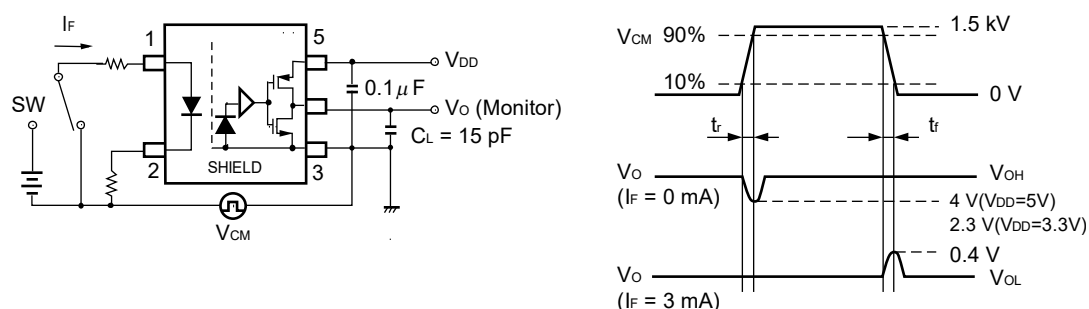
Note2: 1. Typical values at $T_A = 25^\circ\text{C}$

2. Test circuit for propagation delay time measurement



Remark C_L includes probe and stray wiring capacitance.

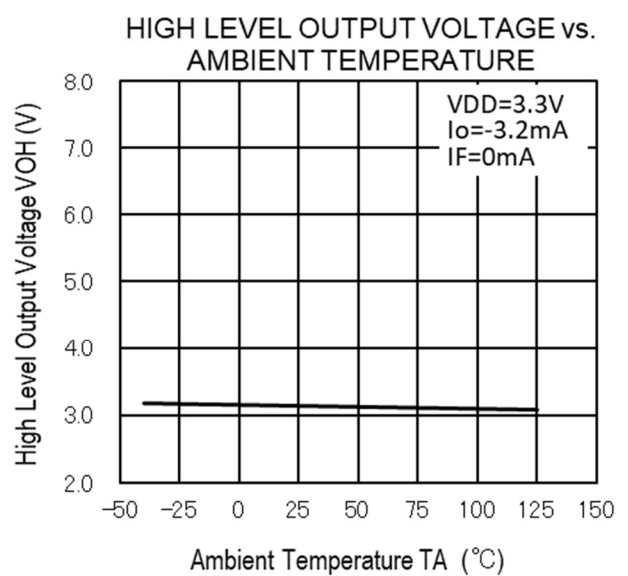
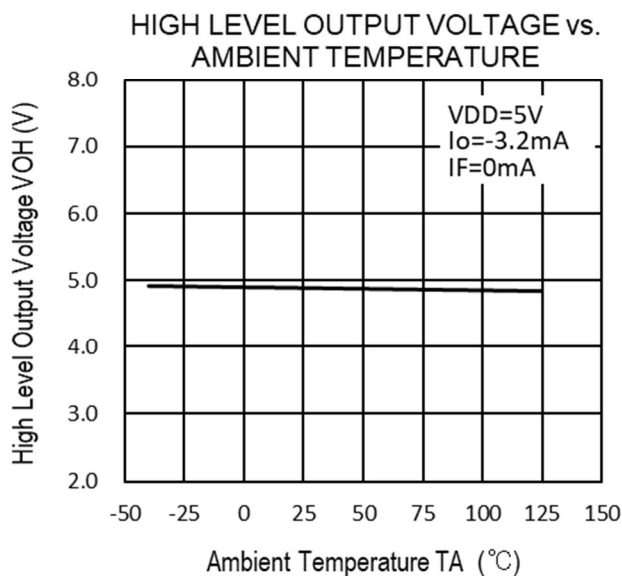
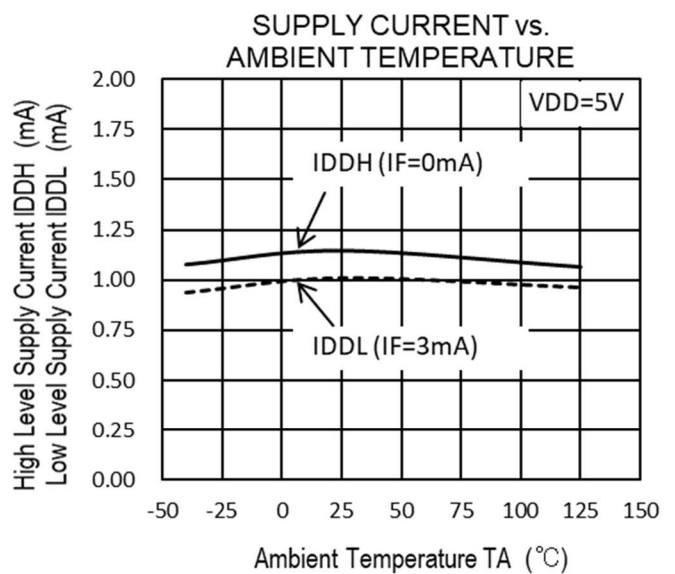
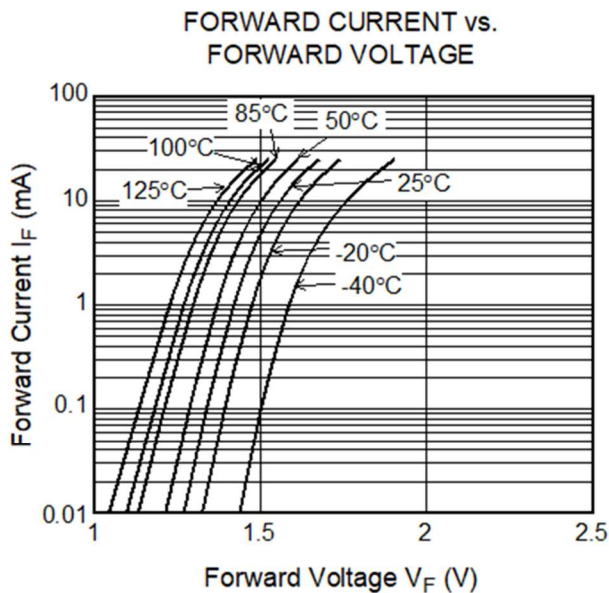
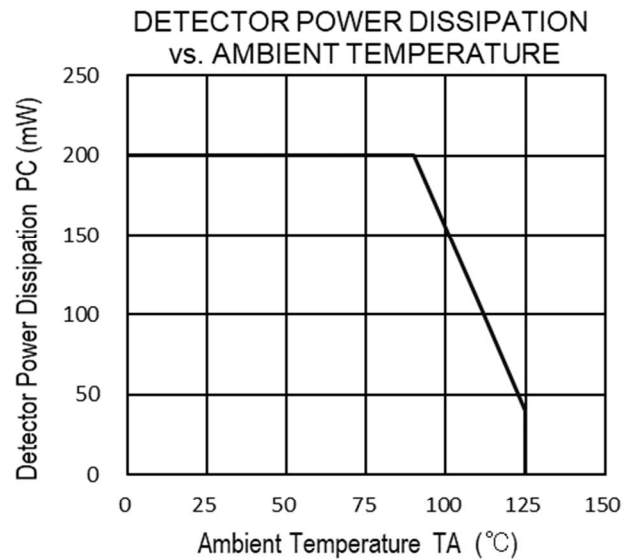
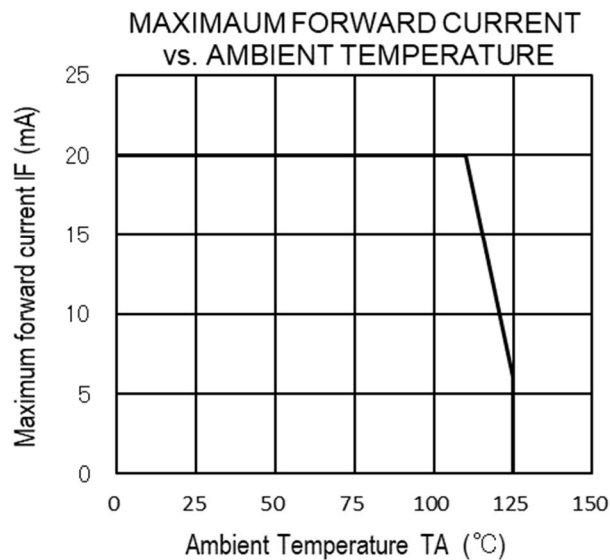
3. Test circuit for common mode transient immunity measurement



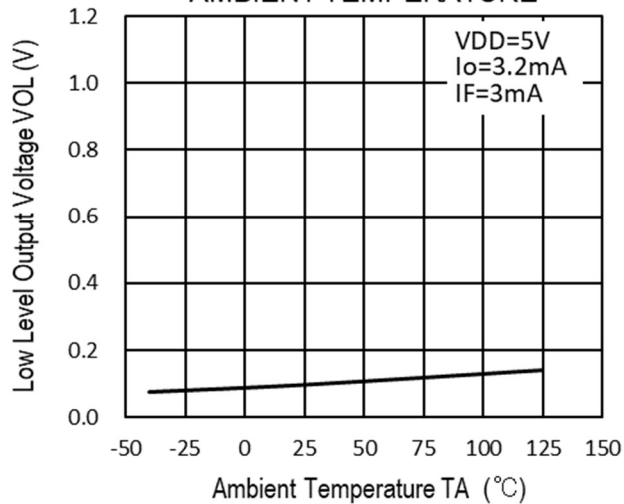
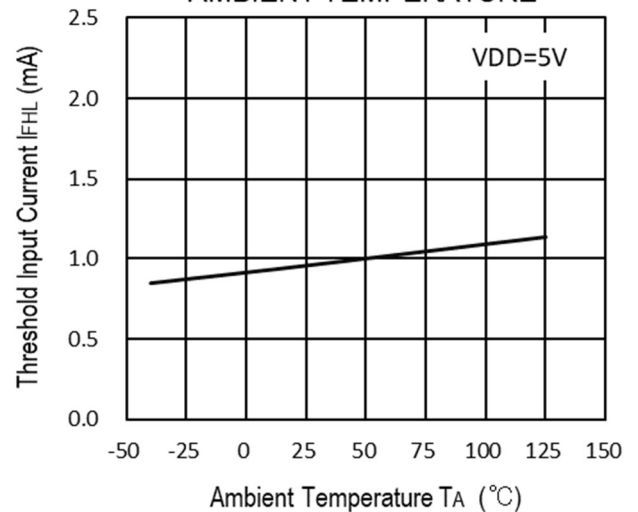
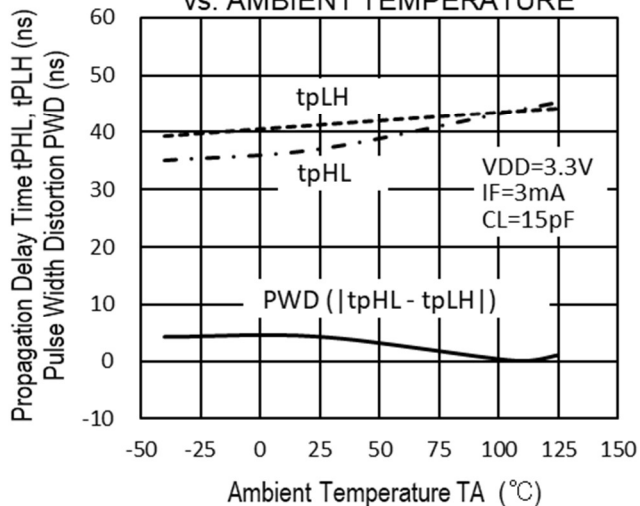
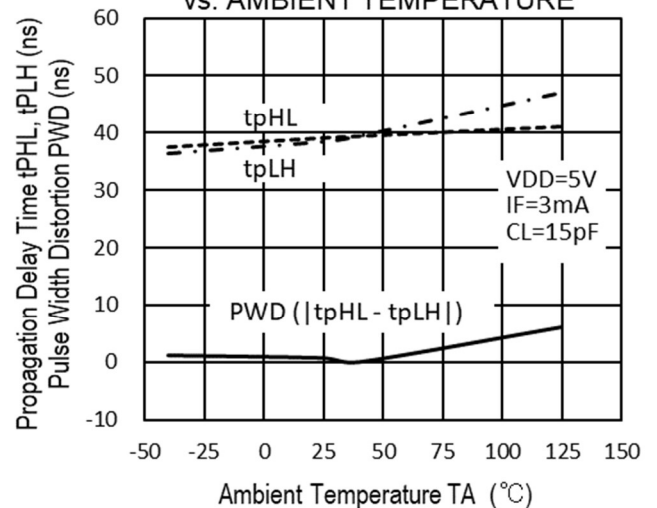
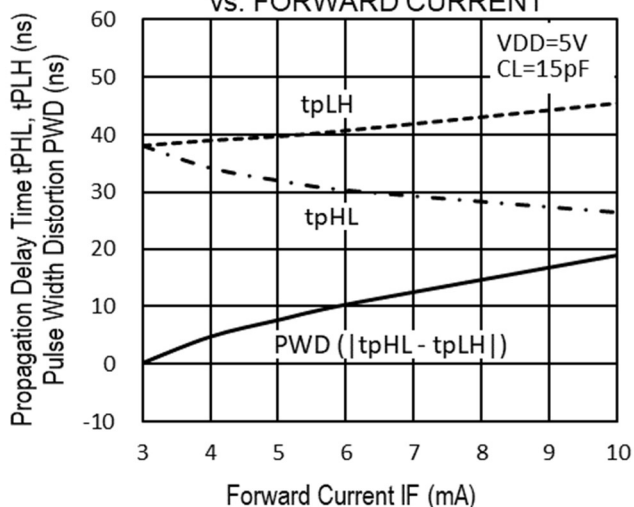
Remark C_L includes probe and stray wiring capacitance.

USAGE CAUTIONS

1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
2. By-pass capacitor of more than $0.1\ \mu\text{F}$ is used between V_{DD} and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
3. Avoid storage at a high temperature and high humidity.

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

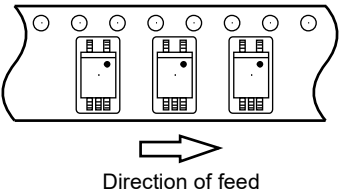
Remark The graphs indicate nominal characteristics.

LOW LEVEL OUTPUT VOLTAGE vs.
AMBIENT TEMPERATURETHRESHOLD INPUT CURRENT vs.
AMBIENT TEMPERATUREPROPAGATION DELAY TIME,
PULSE WIDTH DISTORTION
vs. AMBIENT TEMPERATUREPROPAGATION DELAY TIME,
PULSE WIDTH DISTORTION
vs. AMBIENT TEMPERATUREPROPAGATION DELAY TIME,
PULSE WIDTH DISTORTION
vs. FORWARD CURRENT

Remark The graphs indicate nominal characteristics.

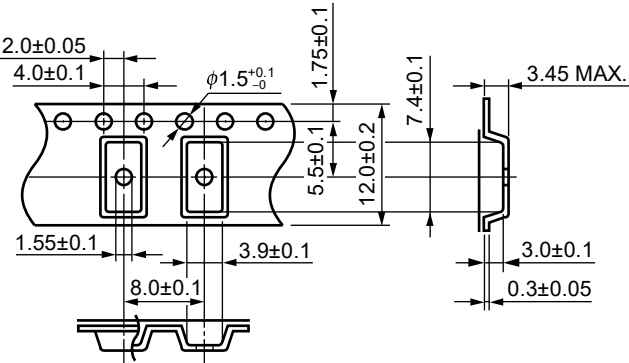
TAPING SPECIFICATIONS (UNIT : mm)

Taping Direction



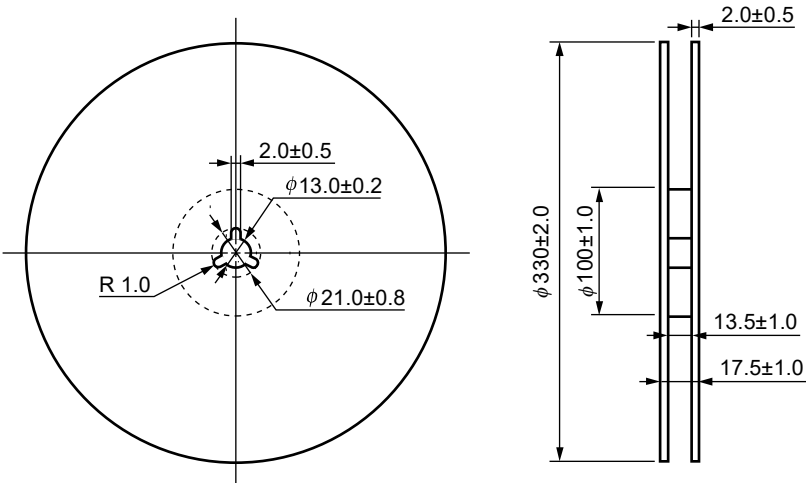
Outline and Dimensions (Tape)

Unit: mm



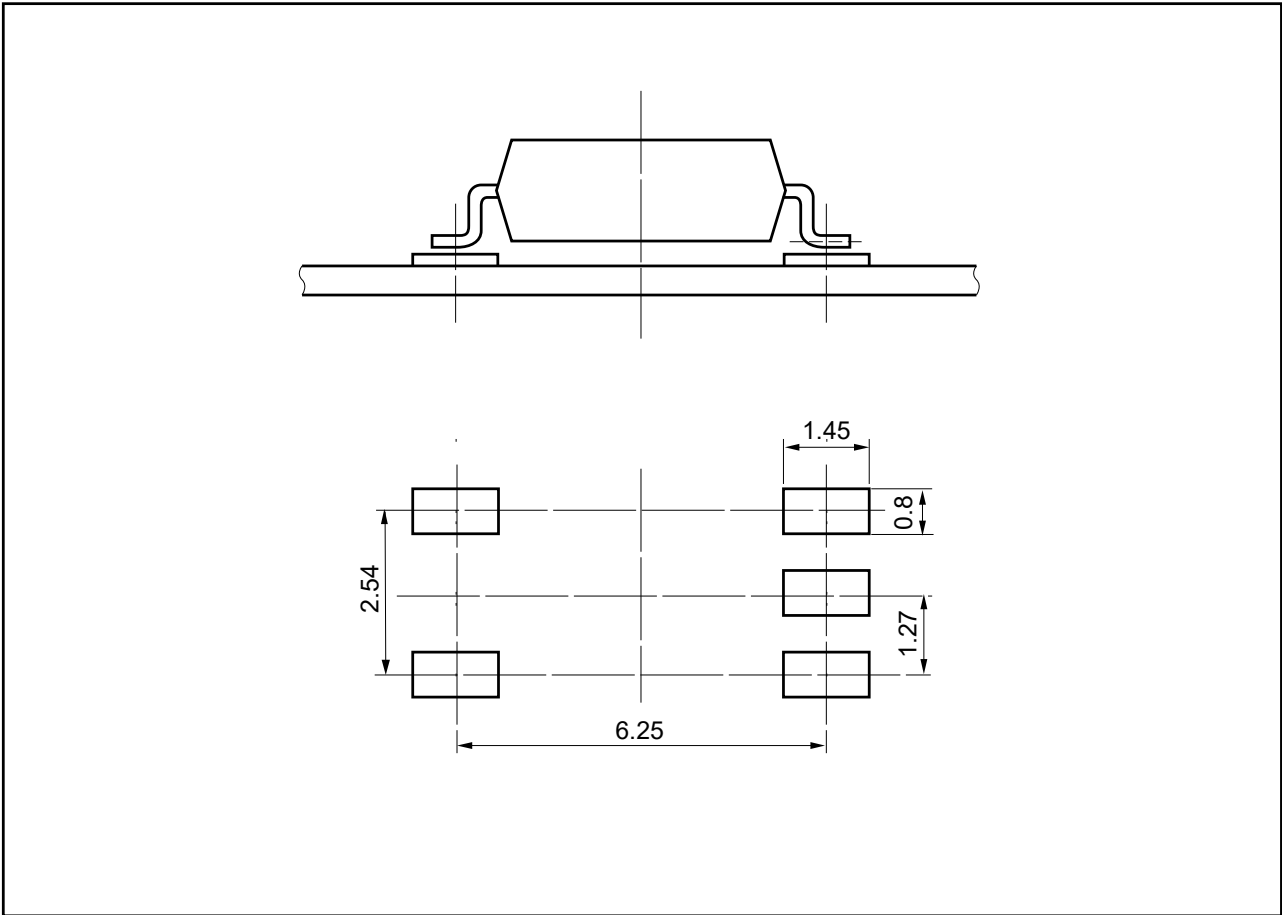
Outline and Dimensions (Reel)

Unit: mm



Packing: 2 500 pcs/reel

RECOMMENDED MOUNT PAD DIMENSIONS (UNIT : mm)



Remark All dimensions in this figure must be evaluated before use.

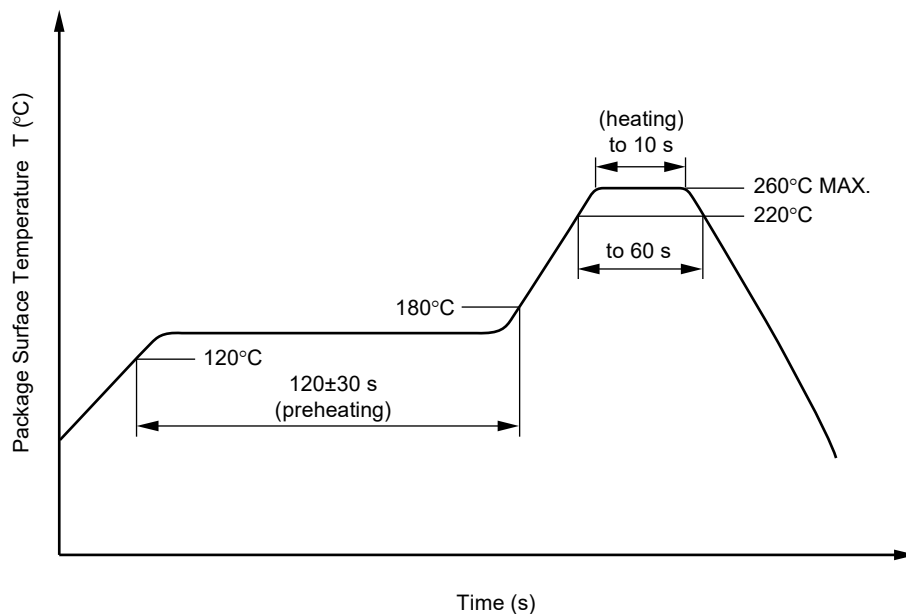
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- | | |
|---|---|
| • Peak reflow temperature | 260°C or below (package surface temperature) |
| • Time of peak reflow temperature | 10 seconds or less |
| • Time of temperature higher than 220°C | 60 seconds or less |
| • Time to preheat temperature from 120 to 180°C | 120±30 s |
| • Number of reflows | Three |
| • Flux | Rosin flux containing small amount of chlorine
(The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- | | |
|-------------------------|--|
| • Temperature | 260°C or below (molten solder temperature) |
| • Time | 10 seconds or less |
| • Preheating conditions | 120°C or below (package surface temperature) |
| • Number of times | One (Allowed to be dipped in solder including plastic mold portion.) |
| • Flux | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

(3) Soldering by Soldering Iron

- | | |
|--|---|
| • Peak Temperature (lead part temperature) | 350°C or below |
| • Time (each pins) | 3 seconds or less |
| • Flux | Rosin flux containing small amount of chlorine
(The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead

(b) Please be sure that the temperature of the package would not be heated over 100°C

(4) Cautions

- Flux Cleaning
Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
- Do not use adhesives or coating materials including halogens to fix this device.

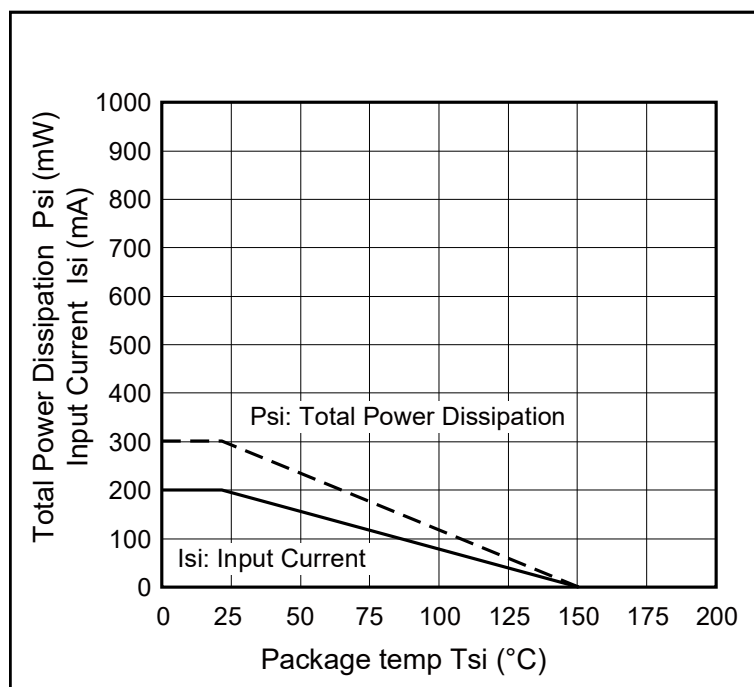
2. Cautions regarding noise

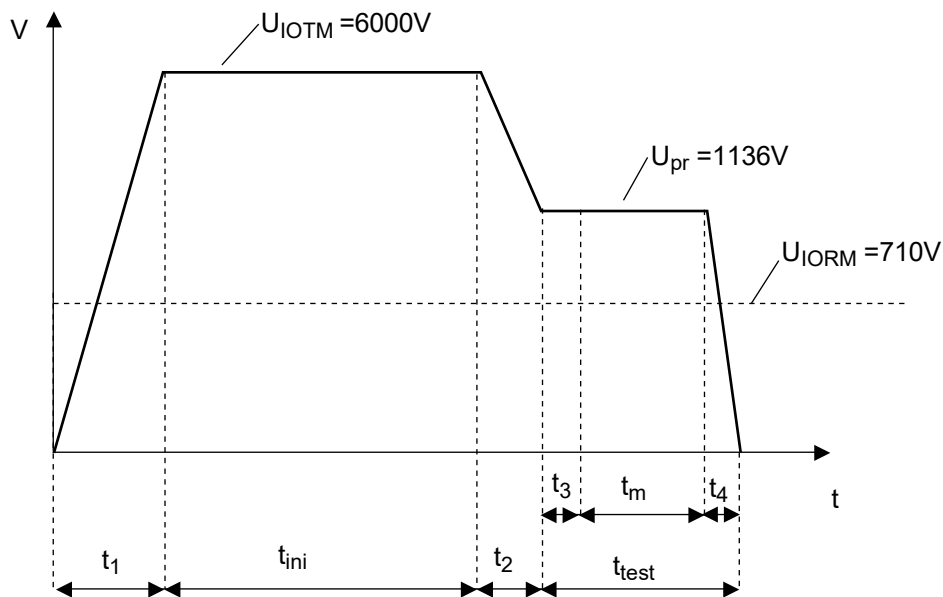
Be aware that when voltage is applied suddenly between the photocoupler's input and output or between V_{DD}-GND at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		40/125/21	
Dielectric strength			
maximum operating isolation voltage	U_{IORM}	710	V_{peak}
Test voltage (partial discharge test, procedure a for type test and random test)	U_{pr}	1 136	V_{peak}
$U_{pr} = 1.6 \times U_{IORM}$, $P_d < 5 \text{ pC}$			
Test voltage (partial discharge test, procedure b for all devices)	U_{pr}	1 331	V_{peak}
$U_{pr} = 1.875 \times U_{IORM}$, $P_d < 5 \text{ pC}$			
Highest permissible overvoltage	U_{IOTM}	6 000	V_{peak}
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	CTI	400	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		II	
Storage temperature range	T_{stg}	- 55 to +150	°C
Operating temperature range	T_A	-40 to +125	°C
Isolation resistance, minimum value			
$V_{IO} = 500 \text{ V dc}$ at $T_A = 25^\circ\text{C}$	Ris MIN.	10^{12}	Ω
$V_{IO} = 500 \text{ V dc}$ at $T_A \text{ MAX.}$ at least 100°C	Ris MIN.	10^{11}	Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve)			
Package temperature	T_{si}	150	°C
Current (input current I_F , $P_{si} = 0$)	I_{si}	200	mA
Power (output or total power dissipation)	P_{si}	300	mW
Isolation resistance			
$V_{IO} = 500 \text{ V dc}$ at $T_A = T_{si}$	Ris MIN.	10^9	Ω

Dependence of maximum safety ratings with package temperature



Method a) Destructive Test, Type and Sample Test

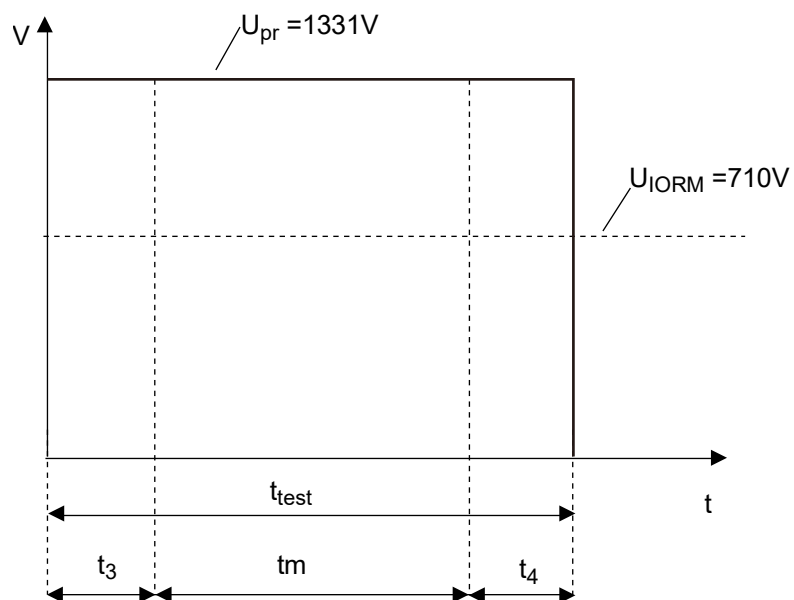
$t_1, t_2 = 1 \text{ to } 10 \text{ sec}$

$t_3, t_4 = 1 \text{ sec}$

$t_m(\text{PARTIAL DISCHARGE}) = 10 \text{ sec}$

$t_{\text{test}} = 12 \text{ sec}$

$t_{\text{ini}} = 60 \text{ sec}$

Method b) Non-destructive Test, 100% Production Test

$t_3, t_4 = 0.1 \text{ sec}$

$t_m(\text{PARTIAL DISCHARGE}) = 1.0 \text{ sec}$

$t_{\text{test}} = 1.2 \text{ sec}$

Caution	GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points. • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.
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(Rev.4.0-1 November 2017)



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